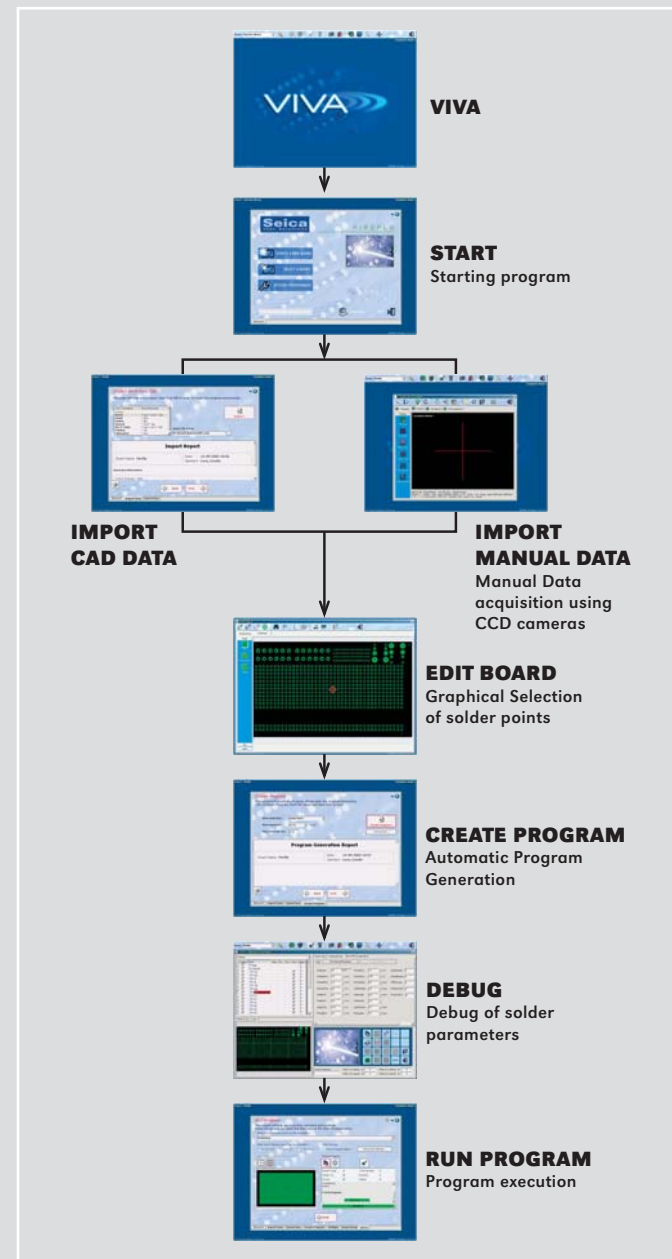




Functional Versatility



www.focusgrafica.it

Last revision: 06/06/07



VIP SELECTIVE SOLDERING

FIREFLY
Line

TECHNICAL CHARACTERISTICS

| | |
|----------------------------|---|
| Laser Unit: | Solid state diode Spot size: 0.3 mm to 6.0 mm Power: maximum 110 W |
| PC: | Intel Pentium IV® CPU LCD 15" Monitor Windows® 2000/XP |
| X-Y axes: | Average Positioning Speed: 500 cm/sec Positioning Resolution: ±3.5 µm Working area: 406 x 508 mm |
| Wire: | 0.5 mm - 0.75 mm - 1 mm Spool: max. 500 g Automatic feed |
| Fume extraction: | 230 m³/h |
| System dimensions: | Length: 1200 mm Depth: 1200 mm Height: 1400 mm Weight: 500 kg |
| Mains: | |
| Power requirements: | 10/230V |
| Power consumption: | 2500W |

Authorized Representative



SEICA Spa
via Kennedy 24 - 10019 Strambino - TO - ITALY
Tel: +39 0125 6368.11 - Fax: +39 0125 6368.99
Email: sales@seica.com

www.seica.com

SEICA FRANCE SARL
24 rue Jean Bart
78960 Voisins le Bretonneux
FRANCE
Tel.: +33 1 39 30 66 77
Fax: +33 1 39 30 66 78
Email: dupoux@seica.com

SEICA Inc.
50A Northwestern Drive
Suite 10 - Salem NH
03079 - USA
Tel: +1 603-890-6002-76-78-79
Fax: +1 603-890-6003
Email: sigillo@seica.com

SEICA ELECTRONICS (Suzhou) Co.Ltd.
XingHan Street Suzhou Industrial Park,
Jiangsu Province, 215021
CHINA
Tel.: +86 512 67610422
Fax: +86 512 67610423
Email: seicachina@seica.com

S e i c a S o l u t i o n s



FIREFLY

FLEXIBILITY via Selective Soldering

The need for efficient production processes has never been so keenly felt as in today's marketplace, and modern production organisations must choose the most cost-effective strategies in a fast-to-market environment.

Firefly is the selective soldering solution that has been developed to satisfy the ever growing need of modern electronics manufacturers for maximum flexibility, and to address the specific issues related to the introduction of the new lead-free alloys.

»» A NEW PRODUCT IN SEICA'S TRADITION

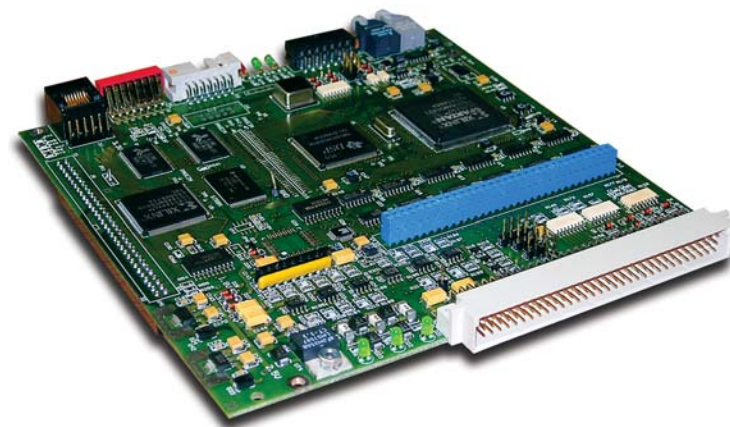
Harnessing the concentrated power that only a laser can generate was the starting point and core of the project that the Seica R&D team developed into the **Firefly**: the modern, efficient and innovative selective soldering solution required by today's industry.

»» THE REAL DIFFERENCE

In today's high-tech industry, comprehensive knowledge and technology make the difference. The quality of components, processes, substrates and consumables, and the interaction between them, are all essential elements which contribute to the quality of the final result: the product.

The positive effect and benefits of integrating the **Firefly** into the manufacturing process are ensured by the integral characteristics of the solution:

- Board and components are soldered correctly without undesirable thermal stress.
- Laser technology allows a non-contact soldering process.
- The accuracy of the thermal process ensures high-quality of solder-joints.
- Soldering is constant and repetitive, and no masking or inert atmosphere are required.
- Ideal for the use of lead-free alloys, and the process totally waste-free.
- High level of process flexibility in all applications.



»» FIELDS OF APPLICATION

Today's industry needs dedicated solutions, specific competences, optimisation of processes and investments. **Firefly** has been designed with the built-in flexibility and performance to make it the ideal selective soldering solution for the electronics manufacturing process, whether it be in the autronics, telecommunications, industrial electronics or medical sector.

The **Firefly** can solder a wide range of components:

- Through hole components
- Pin Grid Array
- Odd form components
- RF shielding
- Connectors

»» SIMPLICITY IN SELECTIVE SOLDERING

Starting from CAD/CAM files, the **Firefly** software automatically extracts the coordinates of the points to be soldered, along with all the other geometrical information used by the internal algorithms to set up the thermal profile, laser spot dimensions and soldering angles, and then to generate the soldering program.

The software also allows the user to create a program manually, aided by the integrated vision system and the interactive guided editor provided by the VIVA software environment.

The editing environment also allows the user to modify the thermal profile and the other variables of each solder joint at any time, according to changing requirements.



It is a new platform based on a unique software and hardware architecture which includes cutting-edge technology ideal for Selective Soldering because it includes:

- VIVA SOFTWARE

The innovative VIVA software organizes the soldering program development into three simple steps:

1. Prepare -> 2. Verify -> 3. Solder which guides the user through a series of automated operations in an intuitive, self-explanatory environment.

- FIBER OPTIC BUS

The proprietary, optical bus included in VIP ensure noise-free communication between real time devices and the system PC.

- PROPRIETARY MOTION DRIVER/CONTROLLERS

VIP includes proprietary motion Driver/controllers that are specifically designed for soldering applications.

